

### 1 Characteristics

Table 1. Absolute maximum ratings (limiting values),  $T_j = 25$  °C unless otherwise specified

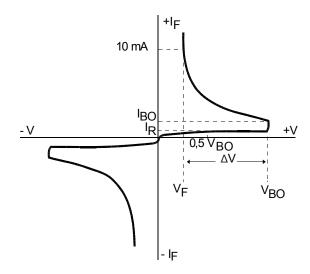
Symbol	Parameter	Value	Unit
I <sub>TRM</sub>	Repetitive peak on-state current, t <sub>p</sub> = 20 μs, F = 120 Hz	2	Α
T <sub>stg</sub>	Storage junction temperature range	-40 to +125	°C
Tj	Operating junction temperature range	-40 to +125	°C

Table 2. Electrical characteristics ( $T_j$  = 25 °C unless otherwise specified)

Symbol	Parameter	Test conditions		Value	Unit
			Min.	28	
V <sub>BO</sub>	Breakover voltage <sup>(1)</sup>	C = 10 nF <sup>(2)</sup>	Тур.	32	V
			Max.	36	
I V <sub>BO1</sub> - V <sub>BO2</sub> I	Breakover voltage symmetry	C = 10 nF <sup>(2)</sup>	Max.	3	V
Δ٧	Dynamic breakover voltage <sup>(1)</sup>	V <sub>BO</sub> and V <sub>F</sub> at 10 mA	Min.	5	V
V <sub>O</sub>	Output voltage <sup>(1)</sup>	See Figure 2. Test circuit , (R = $20 \Omega$ )	Min.	5	V
I <sub>BO</sub>	Breakover current <sup>(1)</sup>	C = 10 nF <sup>(2)</sup>	Max.	50	μA
t <sub>r</sub>	Rise time <sup>(1)</sup>	See Figure 3. Rise time measurement	Max.	2	μs
I <sub>R</sub>	Leakage current <sup>(1)</sup>	$V_R = 0.5 \times V_{BO} \text{ max}$	Max.	10	μΑ
l <sub>P</sub>	Peak current <sup>(1)</sup>	See Figure 2. Test circuit	Min.	0.30	Α

- 1. Applicable to both forward and reverse directions.
- 2. Connected in parallel to the device

Figure 1. Voltage - current characteristic curve.



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Figure 2. Test circuit

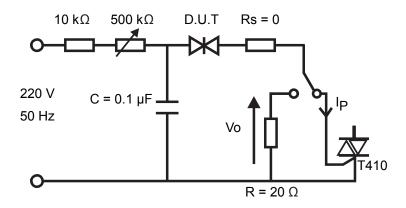
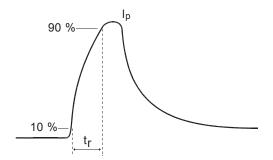


Figure 3. Rise time measurement



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#### 1.1 Characteristics curves

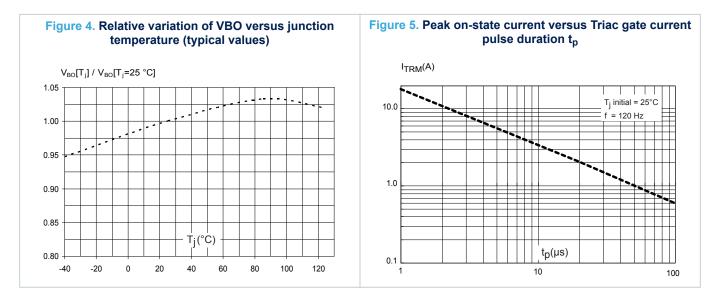
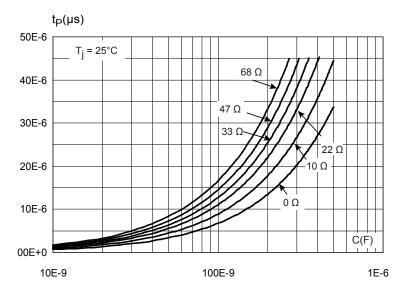


Figure 6. Triac gate current pulse duration  $t_p$  (to have  $I_P > 50$  mA) versus Rs and C values (typical values)



Note: according to Figure 2. Test circuit.

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## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: <a href="https://www.st.com">www.st.com</a>. ECOPACK is an ST trademark.

### 2.1 MINIMELF package information

A ØB

Figure 7. MINIMELF package outline

Table 3. MINIMELF package mechanical data

Dim.	mm					
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	3.30	3.50	3.70	0.130	0.138	0.146
В	1.59	1.65	1.70	0.063	0.065	0.067
С	0.40	0.50	0.60	0.016	0.020	0.024
D		1.50			0.059	

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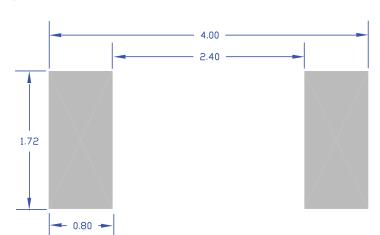


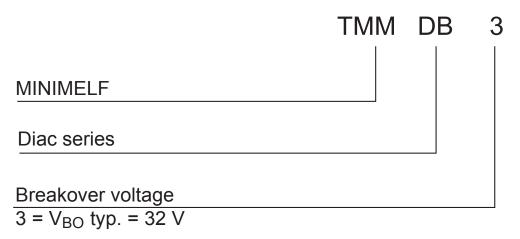
Figure 8. MINIMELF recommended footprint (dimensions are in mm)

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# 3 Ordering information

Figure 9. Ordering information scheme



**Table 4. Ordering information** 

Order code	Marking	Package	Weight	Base qty.	Delivery mode
TMMDB3	NA	MINIMELF	0.049 g	2500	Tape and reel

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## **Revision history**

Table 5. Document revision history

Date	Version	Changes
29-Jan-2009	3	First release.
07-May-2019	4	Updated Table 3 and Figure 8. Minor text change to improve readability.



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